

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2926ign#pbf

(Engineering Calculation)

SSOP

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TOTAL MASS (g) : 0.130469

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003831 | 1000000 | 29363.375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.040238 | 975000 | 308411.25 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000990 | 24000 | 7588.02929688 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000012 | 300 | 91.9761199951 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000029 | 700 | 222.275619507 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.041269 | 1000000 | 316313.53125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002831 | 1000000 | 21695.8867188 | | |
| | | External Plating Total: | | | | 0.002831 | 1000000 | 21695.8867188 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000330 | 1000000 | 2529.34326172 | | |
| Internal Plating Total: | | | | 0.000330 | 1000000 | 2529.34326172 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001080 | 750000 | 8277.85058594 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000360 | 250000 | 2759.28369141 | | |
| Die Attach Total: | | | | 0.001440 | 1000000 | 11037.1347656 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb Free | Resin (EP) | | 0.008259 | 103000 | 63302.5625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.071761 | 895000 | 550024.8125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000160 | 2000 | 1226.3482666 | | |
| | | Encapsulation Total: | | | | 0.080180 | 1000000 | 614553.75 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000588 | 1000000 | 4506.82958984 | | |
| | | | | | TOTAL MASS (g) : | 0.130469 | | |